**APPLICANT:** FANVIL TECHNOLOGY CO., LTD.
**ADDRESS:** LEVEL 3, BLOCK A, GAOXINQI BUILDING, ANHUA INDUSTRIAL PARK, QIANJIN 1 ROAD, 35TH DISTRICT, BAO'AN, SHENZHEN, 518101 P.R. CHINA.

**MANUFACTURE :** FANVIL TECHNOLOGY CO., LTD.
**ADDRESS:** LEVEL 3, BLOCK A, GAOXINQI BUILDING, ANHUA INDUSTRIAL PARK, QIANJIN 1 ROAD, 35TH DISTRICT, BAO'AN, SHENZHEN, 518101 P.R. CHINA.

Report on the submitted sample said to be IP PHONE BRAND NAME: N/A MODEL: C01

**Test Required:** 1)As required by client to determine the Lead,Cadmium,Mercury,Chrimium and Bromine content in the submitted sample.

**Test Method:**

| Testing Item | Testing method | Limit |
|---|---|---|
| Lead (Pb) | With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES | 1000ppm |
| Cadmium (Cd) | With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES | 100ppm |
| Mercury (Hg) | With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES | 1000ppm |
| Hexavalent Chromium (Cr6+) | With reference to IEC62321/2nd CDV (111/95/CDV) ICP-VIS | 1000ppm |
| Polybrominated Biphenyls (PBBs) | With reference to IEC62321/2nd CDV (111/95/CDV) GC-MS | 1000ppm |
| Polybrominated Diphenylethers (PBDEs) | With reference to IEC62321/2nd CDV (111/95/CDV) GS-MS | 1000ppm |

**Results :** Please refer to next pages

**Conclusion :** When tested as specified,the results shown on the report do not exceed the limit in commission decision of 8 June 2011 Directive 2011/65/EU (RoHS 2) on the restriction of the use of certain hazardous substances in electrical and electronic equipment.All data in this report is provided by the manufacture.

Signed for Shenzhen PZD Technology Co.,Ltd.

APPROVED
PZD Technology
Mark Yan/Manager

# RESULT SUMMARY

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

| | Detected content (grade) – See below marks | | | | | | |
|---|---|---|---|---|---|---|---|
| | Parts description | Cr6+ | Cd | Pb | Hg | Br | Conclusion |
| 1 | IC | --- | --- | --- | --- | --- | Declaration |
| 2 | PCB | ND | ND | 10 | ND | ND | Fulfilled |
| 3 | FLASH IC DDR | --- | --- | --- | --- | --- | Declaration |
| 4 | MCU IC | --- | --- | --- | --- | --- | Declaration |
| 5 | IC MEDIA | --- | --- | --- | --- | --- | Declaration |
| 6 | IC POWER | --- | --- | --- | --- | --- | Declaration |
| 7 | IC LDO TOREX | --- | --- | --- | --- | --- | Declaration |
| 8 | OPTICAL COUPLER | ND | ND | ND | ND | ND | Fulfilled |
| 9 | IC POWER TLV | --- | --- | --- | --- | --- | Declaration |
| 10.1 | IC AMP-BODY | ND | ND | 4 | ND | ND | Fulfilled |
| 10.2 | PIN | ND | ND | 10 | ND | --- | Fulfilled |
| 11 | CRYSTAL | ND | ND | ND | ND | ND | Fulfilled |
| 12 | LED | ND | ND | ND | ND | ND | Fulfilled |
| 13.1 | SMD DIODE-BODY | ND | ND | 78472* | ND | ND | Fulfilled |
| 13.2 | SMD DIODE-PIN | ND | ND | 16 | ND | --- | Fulfilled |
| 14 | DIODE | ND | ND | 37.7 | ND | ND | Fulfilled |
| 15 | IO ESD PROTECTOR | --- | --- | --- | --- | --- | Declaration |
| 16 | BEAD | ND | ND | ND | ND | ND | Fulfilled |
| 17 | CEP- PAPER SHEET | ND | ND | 15max | ND | ND | Fulfilled |
| 18 | ADAPTER JACK | ND | ND | 151 | ND | --- | Fulfilled |
| 19 | MLCC | ND | ND | ND | ND | ND | Fulfilled |

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

| | Detected content (grade) – See below marks | | | | | | |
|---|---|---|---|---|---|---|---|
| | Parts description | Cr6+ | Cd | Pb | Hg | Br | Conclusion |
| 20 | MLCC | ND | ND | ND | ND | ND | Fulfilled |
| 21 | MLCC | ND | ND | ND | ND | ND | Fulfilled |
| 22 | MLCC | ND | ND | ND | ND | ND | Fulfilled |
| 23 | RESISTOR | ND | ND | 354 | ND | ND | Fulfilled |
| 24.1 | POWER INDUCTOR CD54-CORE | ND | ND | ND | ND | ND | Fulfilled |
| 24.2 | SN WIRE | ND | ND | 50 | ND | ND | Fulfilled |
| 24.3 | VARNISH | ND | ND | ND | ND | ND | Fulfilled |
| 25.1 | POWER INDUCTOR RH127 SERIES-EPOXY | ND | ND | ND | ND | ND | Fulfilled |
| 25.2 | CORE | ND | ND | ND | ND | ND | Fulfilled |
| 25.3 | CORE | ND | ND | ND | ND | ND | Fulfilled |
| 25.4 | SN WIRE | ND | ND | 50 | ND | ND | Fulfilled |
| 25.5 | VARNISH | ND | ND | ND | ND | ND | Fulfilled |
| 26.1 | NETWORK CABLE-COPPER WIRE | ND | ND | ND | ND | ND | Fulfilled |
| 26.2 | PLUG | ND | ND | ND | ND | ND | Fulfilled |
| 26.3 | PVC PLASTIC | ND | ND | ND | ND | ND | Fulfilled |
| 26.4 | COPPER CONTACT | ND | ND | 12 | ND | ND | Fulfilled |
| 27 | MOSFET AND TRANSISTOR | ND | ND | ND | ND | ND | Fulfilled |
| 28 | CONNECTOR PIN | ND | ND | 37 | ND | --- | Fulfilled |
| 29.1 | RJ45 AND RJ9 CONNECTOR-PBT | ND | ND | ND | ND | ND | Fulfilled |
| 29.2 | COPPER | ND | ND | 9 | ND | --- | Fulfilled |
| 29.3 | GOLD WIRE | ND | ND | ND | ND | ND | Fulfilled |
| 30 | EAR JACK | ND | ND | 151 | ND | --- | Fulfilled |

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

| | Detected content (grade) – See below marks | | | | | | |
|---|---|---|---|---|---|---|---|
| | Parts description | Cr6+ | Cd | Pb | Hg | Br | Conclusion |
| 31.1 | FPC CONNECTOR-WHITE PLASTIC | ND | ND | 6 | ND | ND | Fulfilled |
| 31.2 | DK-BROWN PLASTIC | ND | ND | 6 | ND | ND | Fulfilled |
| 31.3 | SILVERY METAL | ND | ND | 23 | ND | --- | Fulfilled |
| 32.1 | PH2.54 CONNECTOR-ABS PLASTIC | ND | ND | ND | ND | ND | Declaration |
| 32.2 | H53 BRASS PLATE | ND | ND | 246 | ND | --- | Fulfilled |
| 32.3 | PIN | ND | ND | 37 | ND | --- | Fulfilled |
| 33 | MAIN PCB | ND | ND | 3 | ND | ND | Fulfilled |
| 34 | ABS PLASTIC PA757 | ND | ND | ND | ND | ND | Fulfilled |
| 35 | ABS PLASTIC PC-110 | ND | ND | ND | ND | ND | Fulfilled |
| 36.1 | 616E-ABS PLASTIC | ND | ND | ND | ND | ND | Fulfilled |
| 36.2 | WIRE | ND | ND | 14 | ND | --- | Fulfilled |
| 36.3 | PVC PLASTIC BLACK | ND | ND | ND | ND | ND | Fulfilled |
| 36.4 | PVC PLASTIC RED | ND | ND | ND | ND | ND | Fulfilled |
| 36.5 | H52 BRASS PLATE | ND | ND | 346 | ND | --- | Fulfilled |
| 37 | MIC | ND | ND | 24 | ND | ND | Fulfilled |
| 38 | SPONGE | ND | ND | 8 | ND | ND | Fulfilled |
| 39 | RECEIVER | ND | ND | ND | ND | ND | Fulfilled |
| 40 | PAD OF RECEIVER | ND | ND | ND | ND | ND | Fulfilled |
| 41 | DUST NET | --- | --- | --- | --- | --- | Declaration |
| 42 | METAL BLOCK | ND | ND | ND | ND | --- | Fulfilled |

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

| | Detected content (grade) – See below marks | | | | | | |
|---|---|---|---|---|---|---|---|
| | Parts description | Cr6+ | Cd | Pb | Hg | Br | Conclusion |
| 43 | SCREW | ND | ND | ND | ND | --- | Fulfilled |
| 44 | LCD PANEL | --- | --- | --- | --- | --- | Declaration |
| 45 | PET PROTECT FILM | ND | ND | ND | ND | ND | Fulfilled |
| 46 | PMMA | ND | ND | ND | ND | ND | Fulfilled |
| 47 | MARKING LABEL | ND | ND | ND | ND | ND | Fulfilled |
| 48 | ADAPTER | --- | --- | --- | --- | --- | Fulfilled |
| 49 | MANUAL PAPER | ND | ND | ND | ND | ND | Fulfilled |
| 50 | PACKAGE BAG | ND | ND | ND | ND | ND | Fulfilled |
| 51.1 | PACKAGE BOX-<br>PAPER BOARD | ND | ND | ND | ND | ND | Fulfilled |
| 51.2 | INK | ND | ND | ND | ND | ND | Fulfilled |
| 51.3 | INK<br>(RED,YELLOW,BLUE,BLCAK) | ND | ND | ND | ND | ND | Fulfilled |
| 52 | RESISTOR | ND | ND | 668 | ND | ND | Fulfilled |
| 53 | KEY PCB | ND | ND | 8 | ND | ND | Fulfilled |

| Remark |
|---|
| 1. Refer to client information from DECLARATION LETTER |
| 2. Refer to client information SGS:CANEC1301213402 |
| 3. Refer to client information from DECLARATION LETTER |
| 4 Refer to client information from DECLARATION LETTER |
| 5 Refer to client information from DECLARATION LETTER |
| 6 Refer to client information from DECLARATION LETTER |
| 7 Refer to client information from DECLARATION LETTER |
| 8 Refer to client information SGS:CE/2011/B3548 |
| 9 Refer to client information from ON SEMICONDUCTOR DECLARATION LETTER |
| 10 Refer to client information from SGS:CANEC1304007111 |
| 11 Refer to client information SGS:CANEC1110991605 |
| 12 Refer to client information SGS:CE/2011/70009 |
| 13. Refer to client information SGS:CANEC0906214109 |
| 14 Refer to client information SGS:CE/2011/93472 |
| 15 Refer to client information from DECLARATION LETTER |
| 16 Refer to client information SGS:CE/2011/B2759 |
| 17 Refer to client information SGS:CANEC1303384610 |
| 18 Refer to client information CTI:RLSZD000849530002 |
| 19. Refer to client information SGS:CANEC1110605101 |
| 20.Refer to client information SGS:CANEC1110605105 |
| 21.Refer to client information SGS:CANEC1110605104 |
| 22.Refer to client information SGS:KA/2012/C0588 |
| 23.1 Refer to client information CTI:RLSZD000793730001 |
| 23.2 Refer to client information SGS:CANEC1111088220 |
| 23.3 Refer to client information SGS:CE/2011/45621A |
| 24.1 Refer to client information SGS:CANEC1100043507 |

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|---|
| 24.2 Refer to client information CTI:RLSZD000805800001 |
| 24.3 Refer to client information CTI:RLSZD000793730001 |
| 24.4 Refer to client information SGS:CANEC1111088220 |
| 24.5 Refer to client information SGS:CE/2011/45621A |
| 25.1Refer to client information SGS:GZ1103025554/CHEM |
| 25.2 Refer to client information SGS:CE/2012/30567B |
| 25.3 Refer to client information CTI:RLSDD000094790003 |
| 25.4 Refer to client information SGS: CE/2012/30602B |
| 26 Refer to client information SGS:SHAEC1104701505 |
| 27 Refer to client information SGS:CANEC1111180403 |
| 28.1 Refer to client information SGS:CANEC1100504605 |
| 28.2 Refer to client information SGS:CANEC1003851902 |
| 28.3 Refer to client information SGS:SHAEC1018875501 |
| 29.Refer to client information CTI:RLSZD000849530002 |
| 30.Refer to client information SGS:CANEC1102359101 |
| 31.1 Refer to client information CTI:RLSZD000901720001 |
| 31.2 Refer to client information SGS:SHAEC1102754805 |
| 31.3 Refer to client information SGS:CANEC1111180403 |
| 32 Refer to client information SGS:CANEC1101334308 |
| 33 Refer to client information SGS:KA/2011/C1706 |
| 34 Refer to client information SGS:KA/2011/C1777 |
| 35.1 Refer to client information CTI:RLSZD000901720001 |
| 35.2 Refer to client information SGS:CANML1111535001 |
| 35.3 Refer to client information SGS:GZ1110130454/CHEM |
| 35.4 Refer to client information SGS:CANEC1110204416 |
| 35.5 Refer to client information SGS:SHAEC1102754805 |

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|---|
| 36 Refer to client information SGS:CE/2011/22177 |
| 37 Refer to client information SGS:GZ1103018611/CHEM |
| 38 Refer to client information SGS:GZ1104044952/CHEM |
| 39 Refer to client information SGS:GZ1103018609/CHEM |
| 40 Refer to client information from DECLARATION LETTER |
| 41 Refer to client information SGS:CANEC0905103201 |
| 42 Refer to client information SGS:CANEC0802051302 |
| 43 Refer to client information from DECLARATION LETTER |
| 44 Refer to client information SGS:CANEC1103361102 |
| 45 Refer to client information SGS:SHAEC1200148401 |
| 46 Refer to client information SGS:SCATR1103000231 |
| 47 Refer to client information SGS:GZ1108112408/CHEM |
| 48.1 Refer to client information PONY:E12193012704D |
| 48.2 Refer to client information PONY:E12193012904D |
| 49 Refer to client information SGS:SHAEC1101620904 |
| 50 Refer to client information AOV:A001C120210015001-1 |
| 51.1 Refer to client information SGS:GZ1011135401/CHEM |
| 51.2 Refer to client information SGS:GZ1103033406/CHEM |
| 51.3 Refer to client information SGS:GZ1103033412/CHEM |
| 52 Refer to client information SGS:CANEC1102192901 |
| 53 Refer to client information SGS:CANEC1101334301 |

# APPENDIX I

# DECLARATION LETTER FROM DIODES

**Corporate Address:** 4949 Hedgcoxe Road, Suite 110, Plano, TX 75024, USA

**Re:** **End of Vehicle Life Directive (EVL) 2000/53/EC and Annex II (EVL II) 2000/53/EC**
**Restrictions of Hazardous Substances Directive (RoHS) 2002/95/EC & 2011/65/EU**
**Waste Electrical and Electronic Equipment (WEEE)**
**REACH (EC) No 1907/2006**
**Japanese Legislation (Various)**
**China RoHS**
**California Proposition 65**

Diodes Inc. and its subsidiaries including Diodes Zetex Semiconductors Limited have reviewed our manufacturing process and materials along with those of our contractors and suppliers against the above referenced directives.

We hereby declare that all of our products comply fully with the above directives and do not contain any of the following substances except as CURRENTLY exempted* by ELV II and RoHS II:

Asbestos
Azo compounds (Azocolourants and Azodyes)
Cadmium and cadmium compounds CAS No 7440-43-9, EC No 231-152-8
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Dimethyl fumarate
Hexavalent chromium compounds (Chromium VI compounds)
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluoroctane Sulphonate (PFOS)
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes ( > 3 chlorine atoms)
Polychlorinated Terphenyls (PCTs)
Radioactive Substances
Red Phosphorous
Tributyl Tin (TBT) and Triphenyl Tin (TPT), Dibutyltin (DBT) compounds, Dioctyltin (DOT) compounds
Tributyl Tin Oxide (TBTO)

**Our products have never contained PFOS or DecaBDE compounds and no exemptions for these have ever been taken.**

**REACH SVHCs** (in addition to those listed above) (All product versions are REACH Compliant - No SVHCs are present)

| Substance name | CAS number | EC Number |
|---|---|---|
| Anthracene | 120-12-7 | 204-371-1 |
| 4,4'- Diaminodiphenylmethane | 101-77-9 | 202-974-4 |
| Dibutyl phthalate | 84-74-2 | 201-557-4 |
| Chloroethene (vinyl chloride) | 75-01-4 | 200-831-0 |
| Cyclododecane | 294-62-2 | 206-033-9 |
| Cobalt dichloride | 7646-79-9 | 231-589-4 |
| Diarsenic pentaoxide | 1303-28-2 | 215-116-9 |
| Diarsenic trioxide | 1327-53-3 | 215-481-4 |
| Sodium dichromate, dihydrate | 7789-12-0 | |
| 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) | 81-15-2 | 201-329-4 |
| Bis (2-ethyl(hexyl)phthalate) (DEHP) | 117-81-7 | 204-211-0 |
| Hexabromocyclododecane (HBCDD) | 25637-99-4 | 247-148-4 |
| Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins) | 85535-84-8 | 287-476-5 |
| Bis(tributyltin)oxide | 56-35-9 | 200-268-0 |
| Lead hydrogen arsenate | 7784-40-9 | 232-064-2 |
| Triethyl arsenate | 15606-95-8 | 427-700-2 |
| Benzyl butyl phthalate | 85-68-7 | 201-622-7 |

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**REACH ANNEX XVII (including amendments) Substances (All products versions do not contain these substances)**

| Substance name | CAS number | EC Number |
|---|---|---|
| Tris (2,3 dibromopropyl) phosphate | 126-72-7 | |
| Benzene | 71-43-2 | 200-753-7 |
| Asbestos fibres | Multiple, See 2009/552/EC Annex XVII | |
| Tris(aziridinyl)phosphinoxide | 545-55-1 | 208-892-5 |
| Soap bark powder | 68990-67-0 | 273-620-4 |
| Powder of the roots of Helleborus viridis and Helleborus niger Powder of the roots of Veratrum album and Veratrum nigrum | | |
| Benzidine and/or its derivatives | 92-87-5 | 202-199-1 |
| o-Nitrobenzaldehyde | 552-89-6 | 209-025-3 |
| Wood powder | | |
| Ammonium sulphide | 12135-76-1 | 235-223-4 |
| Ammonium hydrogen sulphide | 12124-99-1 | 235-184-3 |
| Ammonium polysulphide | 9080-17-5 | 232-989-1 |
| Methyl bromoacetate | 96-32-2 | 202-499-2 |
| Ethyl bromoacetate | 105-36-2 | 203-290-9 |
| Propyl bromoacetate | 35223-80-4 | |
| Butyl bromoacetate | 18991-98-5 | 242-729-9 |
| 2-Naphthylamine and its salts | 91-59-8 | 202-080-4 |
| Benzidine and its salts | 92-87-5 | 202-199-1 |
| 4-Nitrobiphenyl | 92-93-3 | 202-204-7 |
| 4-Aminobiphenyl xenylamine and its salts | 92-67-1 | 202-177-1 |
| Neutral anhydrous carbonate ($PbCO_3$) | 598-63-0 | 209-943-4 |
| Trilead-bis(carbonate)-dihydroxide $2PbCO_3$-$Pb(OH)_2$ | 1319-46-6 | 215-290-6 |
| $PbSO_4$ | 7446-14-2 | 231-198-9 |
| $PbxSO_4$ | 15739-80-7 | 239-831-0 |
| Arsenic compounds in defined uses | | |
| Organostannic compounds (including those listed in entry 2 of COMMISSION REGULATION (EU) No 276/2010 of 31 March 2010) | | |
| Di-μ-oxo-di-n-butylstanniohydrox-yborane/Dibutyltin – Hydrogen borate $C_8H_{19}BO_3Sn$ (DBB) | 75113-37-0 | 401-040-5 |
| Pentachlorophenol and its salts and esters | 87-86-5 | 201-778-6 |
| Monomethyl — tetrachlorodi-phenyl methane Trade name: Ugilec 141 | 76253-60-6 | |
| Monomethyl-dibromo-diphenyl methane bromobenzylbromo-toluene, mixture of isomers Trade name: DBBT | 99688-47-8 | |
| Nickel (external use where contact with skin can be made) | 7440-02-0 | 231-111-4 |
| Creosote; wash oil | 8001-58-9 | 232-287-5 |
| Creosote oil; wash oil | 61789-28-4 | 263-047-8 |
| Distillates (coal tar), naphthalene oils; naphthalene oil | 84650-04-4 | 283-484-8 |
| Creosote oil, acenaphthene fraction; wash oil | 90640-84-9 | 283-484-8 and 292-605-3 |
| Distillates (coal tar), upper; heavy anthracene oil | 65996-91-0 | 266-026-1 |
| Anthracene oil | 90640-80-5 | 292-602-7 |
| Tar acids, coal, crude; crude phenols | 65996-85-2 | 266-019-3 |
| Creosote, wood | 8021-39-4 | 232-419-1 |
| Low temperature tar oil, alkaline; extract residues (coal), low temperature coal tar alkaline | 122384-78-5 | 310-191-5 |
| Chloroform | 67-66-3 | 200-663-8 |
| 1,1,2-Trichloroethane | 79-00-5 | 201-166-9 |
| 1,1,2,2-Tetrachloroethane | 79-34-5 | 201-197-8 |
| 1,1,1,2-Tetrachloroethane | 630-20-6 | |
| Pentachloroethane | 76-01-7 | 200-925-1 |
| 1,1-Dichloroethene | 75-35-4 | 200-864-0 |
| Hexachloroethane | 67-72-1 | 200-666-4 |
| Alkanes, $C_{10}$-$C_{13}$, chloro (short- chain chlorinated paraffins) (SCCPs) | 85535-84-8 | 287-476-5 |
| Diphenylether, pentabromo derivative $C_{12}H_5Br_5O$ | | |
| Diphenylether, octabromo derivative $C_{12}H_2Br_8O$ | | |
| Nonylphenol $C_6H_4(OH)C_9H_{19}$ | 25154-52-3 | 246-672-0 |

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**REACH ANNEX XVII (including amendments) Substances (All products versions do not contain these substances) (Continued)**

| Substance name | CAS number | EC Number |
|---|---|---|
| Nonylphenol ethoxylates ($C_2H_4O)_nC_{15}H_{24}O$ | | |
| Toluene | 108-88-3 | 203-625-9 |
| Trichlorobenzene | 120-82-1 | 204-428-0 |
| Polycyclic-aromatic hydrocarbons (PAH)(a) Benzo[a]pyrene (BaP) | 50-32-8 | |
| Benzo[e]pyrene (BeP) | 192-97-2 | |
| Benzo[a]anthracene (BaA) | 56-55-3 | |
| Chrysen (CHR) | 218-01-9 | |
| Benzo[b]fluoranthene (BbFA) | 205-99-2 | |
| Benzo[j]fluoranthene (BjFA) | 205-82-3 | |
| Benzo[k]fluoranthene (BkFA) | 207-08-9 | |
| Dibenzo[a,h]anthracene (DBAhA) | 53-70-3 | |
| Bis (2-ethylhexyl) phthalate (DEHP) | 117-81-7 | 204-211-0 |
| Dibutyl phthalate (DBP) | 84-74-2 | 201-557-4 |
| Benzyl butyl phthalate (BBP) | 85-68-7 | 201-622-7 |
| Di-"isononyl" phthalate (DINP) | 28553-12-0 and 68515-48-0 | 249-079-5 and 271-090-9 |
| Di-"isodecyl" phthalate (DIDP) | 26761-40-0 and 68515-49-1 | 247-977-1 and 271-091-4 |
| Di-n-octyl phthalate (DNOP) | 117-84-0 | 204-214-7 |
| 2-(2-methoxyethoxy)ethanol (DEGME) | 111-77-3 | 203-906-6 |
| 2-(2-butoxyethoxy)ethanol (DEGBE) | 112-34-5 | 203-961-6 |
| Methylenediphenyl diisocyanate (MDI) | 26447-40-5 | 247-714-0 |
| Cyclohexane | 110-82-7 | 203-806-2 |
| Ammonium nitrate (AN) | 6484-52-2 | 229-347-8 |
| Dichloromethane | 75-09-2 | 200-838-9 |

**REACH ECHA/PR/09/15 Updates of January 2010 All products versions do not contain these substances)**

| Substance name | CAS number | EC Number |
|---|---|---|
| Anthracene oil | 292-602-7 | 90640-80-5 |
| Anthracene oil, anthracene paste, distn. lights | 295-278-5 | 91995-17-4 |
| Anthracene oil, anthracene paste, anthracene fraction | 295-275-9 | 91995-15-2 |
| Anthracene oil, anthracene-low | 292-604-8 | 90640-82-7 |
| Anthracene oil, anthracene paste | 292-603-2 | 90640-81-6 |
| Pitch, coal tar, high temp. | 266-028-2 | 65996-93-2 |
| Acrylamide | 201-173-7 | 79-06-1 |
| Aluminosilicate Refractory Ceramic | | |
| Zirconia Aluminosilicate, Refractory Ceramic Fibres | | |
| 2,4-Dinitrotoluene | 204-450-0 | 121-14-2 |
| Diisobutyl phthalate | 201-553-2 | 84-69-5 |
| Lead chromate | 231-846-0 | 7758-97-6 |
| Lead chromate molybdate sulphate red (C.I. Pigment Red 104) | 235-759-9 | 12656-85-8 |
| Lead sulfochromate yellow (C.I. Pigment Yellow 34) | 215-693-7 | 1344-37-2 |
| tris(2-chloroethyl)phosphate | 204-118-5 | 115-96-8 |

Perfluorooctane sulfonates (PFOS) C8F17SO2X (X = OH, Metal salt (O-M+), halide, amide, and other derivatives including polymers)

Substances meeting the criteria of flammability in Directive 67/548/ EEC and classified as flammable, highly flammable or extremely flammable regardless of whether they appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 or not.

Substances which appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 classified as carcinogen category 1A or 1B (Table 3.1) or carcinogen category 1 or 2 (Table 3.2) and listed as follows:

- Carcinogen category 1A (Table 3.1)/carcinogen category 1 (Table 3.2) listed in Appendix 1
- Carcinogen category 1B (Table 3.1)/carcinogen category 2 (Table 3.2) listed in Appendix 2

Substances which appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 classified as germ cell mutagen category 1A or 1B (Table 3.1) or mutagen category 1 or 2 (Table 3.2) and listed as follows:

- Mutagen category 1A (Table 3.1)/mutagen category 1 (Table 3.2) listed in Appendix 3
- Mutagen category 1B (Table 3.1)/mutagen category 2 (Table 3.2) listed in Appendix 4

**REACH ECHA/PR/09/15 Updates of January 2010 (Continued)**

Substances which appear in Part 3 of Annex VI to Regulation (EC) No 1272/2008 classified as toxic to reproduction category 1A or 1B (Table 3.1) or toxic to reproduction category 1 or 2 (Table 3.2) and listed as follows:

- Reproductive toxicant category 1A adverse effects on sexual function and fertility or on development (Table 3.1) or reproductive toxicant category 1 with R60 (May impair fertility) or R61 (May cause harm to the unborn child) (Table 3.2) listed in Appendix 5
- Reproductive toxicant category 1B adverse effects on sexual function and fertility or on development (Table 3.1) or reproductive toxicant category 2 with R60 (May impair fertility) or R61 (May cause harm to the unborn child) (Table 3.2) listed in Appendix 6

Substances or mixtures, which are regarded as dangerous according to the definitions in European Union Directives 67/548/EEC and 1999/45/EC.

**REACH Updates ED/30/2010 of June 2010 (All product versions are REACH Compliant - No SVHCs present)**

| Substance name | CAS Number | EC Number |
|---|---|---|
| Trichloroethylene | 79-01-6 | 201-167-4 |
| Boric acid | 10043-35-3 | 233-139-2 |
| | 11113-50-1 | 234-343-4 |
| Disodium tetraborate, anhydrous | 1303-96-4 | 215-540-4 |
| | 1330-43-4 | |
| | 12179-04-3 | |
| Tetraboron disodium heptaoxide, hydrate | 12267-73-1 | 235-541-3 |
| Potassium dichromate | 7778-50-9 | 231-906-6 |
| Ammonium dichromate | 7789-09-5 | 232-143-1 |
| Potassium chromate | 7789-00-6 | 232-140-5 |
| Sodium chromate | 7775-11-3 | 231-889-5 |

**REACH Updates ED/95/2010 of December 2010 (All product versions are REACH Compliant - No SVHCs present)**

| Substance name | CAS Number | EC Number |
|---|---|---|
| Cobalt(II) sulphate | 10124-43-3 | 233-334-2 |
| Cobalt(II) dinitrate | 10141-05-6 | 233-402-1 |
| Cobalt(II) carbonate | 513-79-1 | 208-169-4 |
| Cobalt(II) diacetate | 71-48-7 | 200-755-8 |
| 2-Methoxyethanol | 109-86-4 | 203-713-7 |
| 2-Ethoxyethanol | 110-80-5 | 203-804-1 |
| Chromium trioxide | 1333-82-0 | 215-607-8 |
| Chromic acid, Oligomers of chromic acid and dichromic acid, Dichromic acid | 7738-94-5 | 231-801-5 |
| | 13530-68-2 | 236-881-5 |

**REACH Updates ED/31/2011 of June 2011 (All product versions are REACH Compliant - No SVHCs present)**

| Substance name | CAS Number | EC Number |
|---|---|---|
| Cobalt dichloride | 7646-79-9 | 231-589-4 |
| 1,2-Benzenedicarboxylic acid, di-C6-8-branched alkyl esters, C7-rich | 71888-89-6 | 276-158-1 |
| 1,2,3-Trichloropropane | 96-18-4 | 202-486-1 |
| 1-Methyl-2-pyrrolidone | 872-50-4 | 212-828-1 |
| Hydrazine | 302-01-2 / 7803-57-8 | 206-114-9 |
| 1,2-Benzenedicarboxylic acid, di-C7-11-branched and linear alkyl esters | 68515-42-4 | 271-084-6 |
| Strontium chromate | 7789-06-2 | 232-142-6 |
| 2-Ethoxyethyl acetate | 111-15-9 | 203-839-2 |

**REACH Updates ED/77/2011 of December 2011 (All product versions are REACH Compliant - No SVHCs present)**

| Substance name | CAS Number | EC Number |
|---|---|---|
| 1,2-Dichloroethane | 107-06-2 | 203-458-1 |
| 2,2'-Dichloro-4,4'-methylenedianiline | 101-14-4 | 202-918-9 |
| 2-Methoxyaniline; o-Anisidine | 90-04-0 | 201-963-1 |
| 4-(1,1,3,3-Tetramethylbutyl) phenol; 4-tert-octyl phenol | 140-66-9 | 205-426-2 |
| Aluminosilicate Refractory Ceramic Fibres | - | - |
| Arsenic acid | 7778-39-4 | 231-901-9 |
| Bis(2-methoxyethyl) ether | 111-96-6 | 203-924-4 |
| Bis(2-methoxyethyl) phthalate | 117-82-8 | 204-212-6 |
| Calcium arsenate | 7778-44-1 | 231-904-5 |
| Dichromium tris(chromate) | 24613-89-6 | 246-356-2 |
| Formaldehyde, oligomeric reaction products with aniline | 25214-70-4 | 500-036-1 |
| Lead diazide, Lead azide | 13424-46-9 | 236-542-1 |
| Lead dipicrate | 6477-64-1 | 229-335-2 |
| Lead styphnate | 15245-44-0 | 239-290-0 |
| N,N-dimethylacetamide | 127-19-5 | 204-826-4 |
| Pentazinc chromate octahydroxide | 49663-84-5 | 256-418-0 |
| Phenolphthalein | 77-09-8 | 201-004-7 |
| Potassium hydroxyoctaoxodizincatedichromate | 11103-86-9 | 234-329-8 |
| Trilead diarsenate | 3687-31-8 | 222-979-5 |
| Zirconia Aluminosilicate Refractory Ceramic Fibres | - | - |

**U.S. Department of Labor Federal Standard 29 – CFR Part 1910.1000 and other Substances:**

Our products do not contain the following substances (in addition to those stated above):

| Substance name | CAS Number |
|---|---|
| 4-Nitrobiphenyl | 92-93-3 |
| alpha-Naphthylamine | 134-32-7 |
| methyl chloromethyl ether | 107-30-2 |
| 3,3'-Dichlorobenzidine (and its salts) | 91-94-1 |
| bis-Chloromethyl ether | 542-88-1 |
| beta-Naphthylamine | 91-59-8 |
| Benzidine | 92-87-5 |
| 4-Aminodiphenyl | 92-67-1 |
| Ethyleneimine | 151-56-4 |
| beta-Propiolactone | 57-57-8 |
| 2-Acetylaminofluorene | 53-96-3 |
| 4-Dimethylaminoazo-benzene | 60-11-7 |
| N-Nitrosodimethylamine | 62-75-9. |

- Columbite-tantalite, cassiterite or wolframite or derivatives

**GADSL: (Global Automotive Declarable Substance List)**

Diodes Incorporated's products may contain permutations of the following substances:

**Arsenic:** Is used as a dopant in the "chip" or "die".
**Antimony Trioxide:** Is used as a part of the flame retardant system in non-green product.
**Copper:** Some products use copper in the leadframe alloy, some others have a copper-plated Alloy 42 leadframe. Copper is increasingly being used internally in product to form connections between the die and the leadframe.
**Lead:** Some products have a high temperature solder die attach >85% lead, some have lead in the die passivation or the glass encapsulation, others have lead in the copper leadframe alloy. All of these applications are exempted from RoHS.

**Rare Earth Metals:**

Our products do not contain:

Scandium, Yttrium, Lanthanum, Cerium, Praseodymium, Neodymium, Promethium, Samarium, Europium, Gadolinium, Terbium, Dysprosium, Holmium, Erbium, Thulium, Ytterbium, Ruthenium.

**Japanese Laws:**

No. 117, 1973, as last amended by Law No.49, 2003. Our products do not contain:

- N,N'> -ditoryl-para-phenylenediamine>
- N-tolyl-N'> -xylyl-para-phenylenediamine
- N> '> -dixyl-paraphenyllenediamine (CAS # 15017-02-4)

No. 32 of September 30, 1972 and Ministry of Health, Labour and Welfare Ordinance No. 47 of March 30, 2007 from the Japan International Center for Occupational Safety and Health. Our products do not contain:

- Mirex > -> CAS # 2385-85-5
- Benzidine and its salts CAS numbers 531-85-1, 92-87-5, 531-86-2
- Benzene paste (benzene 5% or more)

No. 138 of 1970, Water Pollution Control Law, Latest Amendment by Law No. 75 of 1995. Our products do not contain:

- Cyanogen compounds

**California Proposition 65**

Certain Diodes Inc. products contain lead and/or nickel. These are wholly contained within the devices.

**"Green"** or **"halogen-free"** product is defined as:

RoHS and REACH Compliant
Bromine <900ppm, Chlorine <900ppm, Bromine+Chlorine <1500ppm, Antimony Compounds <1000ppm.

* **The following applicable exemptions are currently outlined in EVL II and RoHS II:**

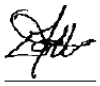
Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
(Some Diodes Inc. products use this type of solder internally for die attach purposes)

Aluminium containing up to 0,4 % lead by weight,
Copper alloy containing up to 4 % lead by weight

Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.
(Some Diodes Inc. products contain glass passivation at the die level and glass packages contain PbO in the glass)

RoHS exemptions are to be reviewed and may be subject to change at least every four years. Renewal of Exemptions is expected where no viable alternative material is available.

Our products may contain traces of any substance not purposely added and below reporting or detection levels.



David Fitton
Compliance Coordinator

Date: 1 March 2012

Diodes Incorporated
4949 Hedgcoxe Road, Suite 110, Plano, TX 75024, USA
Tel: 972 987 3900

Diodes Zetex Semiconductors Limited
Chadderton, Oldham, OL9 9LL United Kingdom
Tel: (44) 161 622 4444
Fax: (44) 161 622 4446

Diodes Inc. Taiwan
Hsin-Tien, Taipei, Taiwan, R.O.C.
Tel: 011-886-2-8914-6000
Fax: 011-886-2-8914-6639

# DECLARATION LETTER FROM SAMSUNG

**Samsung Electronics Co., LTD.**
San #16 Banwol-Dong, Taean-Gu Hwasung-City, Gyeonggi-Do, KOREA 445-330
Tel. +82-31-208-5825, Fax. +82-31-208-6388, Mailto: sy.jung@samsung.com

| | |
|---|---|
| **To** | All customers |
| **From** | SAMSUNG ELECTRONICS CO.LTD. |
| **Date** | 2011-10-11 |
| **Subject** | **Declaration of RoHS Compliance** |
| **Manufacturer Product** | **All Samsung memory** |

Samsung Electronics Co. Ltd (the company) hereby declares that the product(s) described above is(are) compliant with the European Union Directive 2002/95/EC for Restriction of the use of certain Hazardous Substances in Electrica and Electronic Equipment (RoHS Directive).

RoHS compliant means that where the product falls under the scope of the EU RoHS Directive, this product does not contain the following substances:

- Mercury ( Hg ) 0.1%
- Lead ( Pb ) 0.1%
- Cadmium ( Cd ) 0.01%
- Hexavalent Chromium ( Cr+6) 0.1%
- Polybrominated Biphenyls ( PBB ) 0.1%
- Polybrominated Diphenyl Ethers ( PBDE ) 0.1%

in excess of the indicated maximum concentration values by weight in homogenous materials, unless the substance is subject to an exemption specified in the Directive.

This declaration represents the Company's knowledge and belief which is partially based on information provided by third party suppliers.

Further details about Samsung Electronics' RoHS compliance programme can be found at:
http://www.samsung.com/eco-semi

Regards,

Sang Yun Jung
Environmental Senior Manager
Environment, Safety & Health Team

# DECLARATION LETTER FROM FREESCALE

Freescale Semiconductor Inc

| PART INFORMATION | |
|---|---|
| Mfg Item Number | MCIMX6Q5EYM10AC |
| Mfg Item Name | FCPBGA 624 21*21*1.45P.8 |

| SUPPLIER | |
|---|---|
| Company Name | Freescale Semiconductor Inc |
| Company Unique ID | 14-141-7928 |
| Response Date | 2013-03-14 |
| Response Document ID | 009UK10737D166A1.3 |
| Contact Name | Freescale Semiconductor Inc |
| Contact Title | Product Technical Support |
| Contact Phone | 1-800-521-6274 |
| Contact Email | support@freescale.com |
| Authorized Representative | Daniel Binyon |
| Representative Title | EPP Customer Response |
| Representative Phone | 512-895-3406 |
| Representative Email | eppanlst@freescale.com |
| URL for Additional Information | www.freescale.com |

| DECLARATION | |
|---|---|
| EU RoHS | Yes |
| Pb Free | Yes |
| HalogenFree | Yes |
| Plating Indicator | e1 |
| EU RoHS Exemption(s) | |

| MANUFACTURING | |
|---|---|
| Mfg Item Number | MCIMX6Q5EYM10AC |
| Mfg Item Name | FCPBGA 624 21*21*1.45P.8 |
| Version | ALL |
| Weight | 1.287100 |
| UoM | g |
| Unit Volume | EACH |
| J-STD-020 MSL Rating | 3 |
| Peak Processing Temperature | 260 C |
| Max Time at Peak Temperature | 40 seconds |
| Number of Processing Cycles | 3 |

| RoHS | |
|---|---|
| RoHS Directive | 2011/65/EU |
| RoHS Definition | RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium |
| RoHS Legal Definition | Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply. |
| RoHS Declaration | 1 - Item(s) do not contain RoHS restricted substances per the definition above |
| Supplier Acceptance | Accepted |
| Signature | Daniel Binyon |
| | |
| Exemptions in this part | |
| List of Freescale Accepted Exemptions | 6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight<br>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight<br>6(c) : Copper alloy containing up to 4% lead by weight<br>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)<br>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications<br>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound<br>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher<br>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC<br>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors<br>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages |

# DECLARATION LETTER FROM TOREX

TOREX

*Torex...Powerfully Small!*

**TOREX Semiconductor Ltd.**
Sakura Nihonbashi Bldg. 8F
1-13-12, Nihonbashi, Kayabacho
Chuo-Ku, Tokyo 103-0025
Japan
Phone: +81-3-5652-8725
Fax: +81-3-5652-8731
http://www.torex.co.jp

**Certificate of EU RoHS Compliance**

We hereby assure that all products from TOREX do not intentionally contain any of the RoHS-referred substances listed below (except for exempted applications by the directive).

- Cadmium
- Lead
- Mercury
- Hexavalent chromium
- PBB
- PBDE

For any inquiries regarding this issue, please contact our sales dept.

Takara Yoshida
Director, Quality Assurance Dept.

# DECLARATION LETTER SILICONLABS

## Certificate of RoHS Compliance

March 19, 2012

Silicon Laboratories certifies that the device listed below is compliant with the European Union Directive 2002/95/EC for the Restriction of the use of certain Hazardous Substances in Electrical and Electronic Equipment (RoHS).

SI32176-B-FM1

No Lead (Pb), Cadmium (Cd), Mercury (Hg), Hexavalent Chromium (Cr+6), PBB or PBDE is intentionally added to this device. Any trace impurities of these substances contained in the part are below the RoHS specified threshold levels:

Cr+6, Hg, Pb, PBB's, PBDE's < 1000ppm
Cd < 100ppm

All information provided in this Certificate of Compliance is accurate, to the best of our knowledge, as of the date this certification was issued.

Sandeep P. Kumar
Vice President of Quality and Operations Engineering

400 W. Cesar Chavez St.
Austin, Texas 78701
Phone (512) 416-8500
Fax (512) 416-9669
www.silabs.com

# DECLARATION LETTER FROM ON SEMICONDUCTOR

ON Semiconductor has completed most of its component conversions of its products for the customers who must meet the requirements of the European Union Directive "Restriction on Use of Hazardous Substances in Electrical and Electronic Equipment," or "RoHS" directive 2011/65/EU, which has an implementation date of January 1, 2013. We are committed to provide information about substances in its products as required and will continue to monitor and respond to other environmental directive developments to ensure our customer needs are met in a timely manner. Visit our web site http://www.onsemi.com/PowerSolutions/MaterialComposition.do by searching for its orderable part number for detailed material composition, based on the homogenous or piece parts contained in its products.

In addition to meeting European RoHS requirements, we are in compliance to the People's Republic of China Electronic Industry Standard "Management Methods for the Control of Pollution from Electronic Information Products" (also known as China RoHS) reporting requirements since March 2007. Our bar code shipping labels contain additional information regarding hazardous material content complying with the China RoHS directive.

Additional information displayed on our shipping labels are:

The  symbol with an  symbol will mean truly Pb free throughout the entire component. The  symbol will be added to the labels of components that contain lead, either in the termination finish or in the die attach. Parts may have the  symbol with RoHS=Y, and the  symbol, meaning termination finish is lead (Pb) free, but the die attach contains lead (Pb).

The number 50 is an industry agreed upon number that refers to the number of years a semiconductor unit can exist before it potentially releases hazardous substances into the environment.

# DECLARATION LETTER FROM SUNLORD

ROHS Sunlord Electronics 页码，1/1

Sunlord
EXPERT IN PASSIVE PARTS

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Free Sample >>


ROHS COMPLIANT

NEW Power Inductor with Ultra Low DC Resistance Details>

Home > ROHS

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## Ⅰ. HS Overview

### Definition

A generic definition of a hazardous substance is provided by the Australian Safety and Compensation Council (ASCC) as "a substance which has the potential, through being used at work, to harm the health or safety of persons in the workplace".

### Control of Hazardous Substances

For the purpose of protecting the environment and human health, the Directive on the restriction of the use of certain hazardous substances in electrical and electronic equipment 2002/95/EC; commonly referred to as RoHS) was adopted in 2003 by the European Union. The RoHS directive took effect on 1 July 2006, and is required to be enforced and become law in each member state. This directive restricts the use of six hazardous materials in the manufacture of various types of electronic and Electrical equipment. It is closely linked with the WasteElectrical and Electronic Equipment Directive (WEEE) 2002/96/EC which sets collection, recycling targets for electrical goods to solve the problem of huge amount of toxic e-waste.

### REACH

There is no doubt that the use of chemicals in all fields speed up the development of human society, however, which also bring about potential influences to human body & the environment, then EU issued "Registration, Evaluation, Authorization and Restriction of Chemicals" in March, 2003 aiming to standardize the application of chemicals.

### Increased Hazardous Substances and Enlarged Application Area

More and more hazardous substances, such as halogen are brought under control along with the industry development. Other countries or regions also established a series of regulations to restrict the use of hazardous substances, like Proposition 65 and Chinese RoHS etc. .

## Ⅱ. The Links between Our Products and Hazardous Substances

### HSF Policy

To protect the only living environment for human, the earth, we declare that the products manufactured by Sunlord comply with the requirements of SONY SS-00259, EU RoHS and related customers.

Sunlord has gained the certificates of Sony GP & QC080000 successfully, and established an effective management system.

**CEATEC JAPAN 2011**
Date: October 4th-8th, 2011

Location: 2-1, Nakase, Mihama-ku, Chiba-city, 261-0023 Japan

Booth: 6E35


Aerospace


Automotive


Technology

Frequently Asked Questions

 Mail System

News | Products | Privacy Policy | About Sunlord

# DECLARATION LETTER FROM FZB

1/1

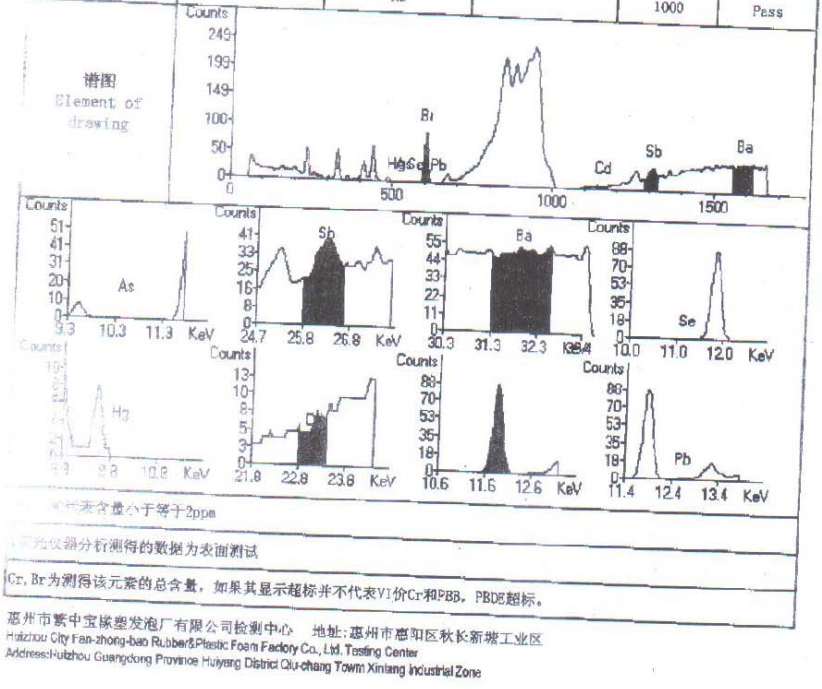
FZB 环保

全分析报告

Total Analysis Report

| 样品名称 Sample Name | 防尘网 | 测量时间 Test Time | 200 | [redacted] | |
|---|---|---|---|---|---|
| 供应商 Supplier | | 管压 Voltage | 45 | | |
| 操作员 Operator | FZB | 管流 Current | 400 | | |
| 测量日期 Test Date | 2011-5-11 | 工作曲线 WorkCurve | PE | | |
| 批号 LotNo. | | 仪器型号 Mode | edx1800 | | |
| 元素 Element | 强度 Intensity | 含量(ppm) Content(ppm) | 误差(ppm) Error(ppm) | 限定标准 Limits | 判定 Results |
| As | 0.00E+00 | ND | | 1000 | Pass |
| Sb | 1.05E-02 | 85.2 | 2.26 | — | — |
| Ba | 1.83E-03 | 47.3 | 0.83 | — | — |
| Sc | 0.00E+00 | ND | | — | — |
| Hg | 0.00E+00 | ND | | 1000 | Pass |
| Cd | -2.36E-04 | ND | | 100 | Pass |
| Br | 2.43E-02 | 95.3 | 2.9 | 1000 | Pass |
| Pb | 0.00E+00 | ND | | 1000 | Pass |

谱图 Element of drawing



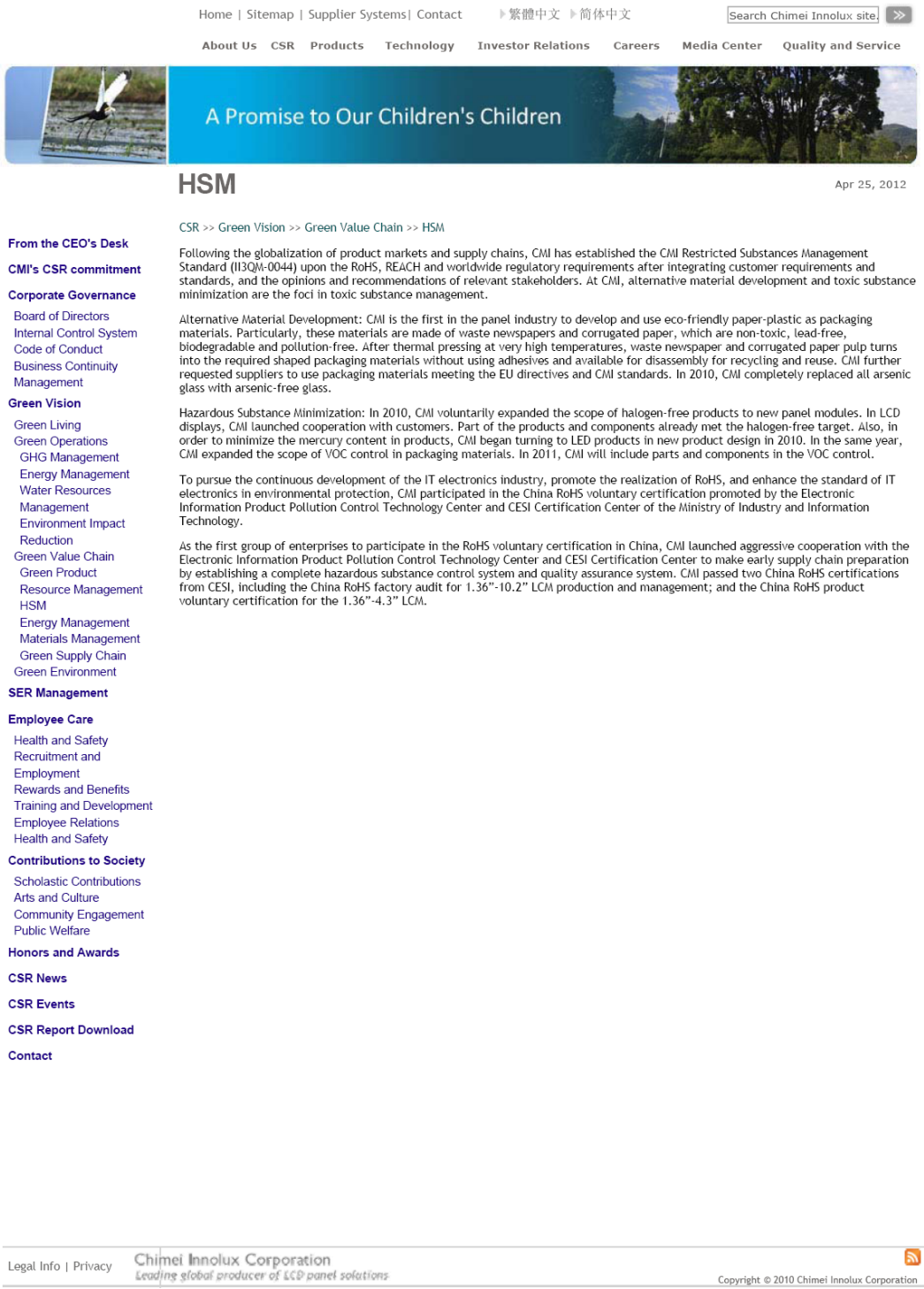

Cr, Br为测得该元素的总含量，如果其显示超标并不代表VI价Cr和PBB，PBDE超标。

惠州市繁中宝橡塑发泡厂有限公司检测中心 地址：惠州市惠阳区秋长新塘工业区

Huizhou City Fan-zhong-bao Rubber&Plastic Foam Factory Co., Ltd. Testing Center

Address:Huizhou Guangdong Province Huiyang District Qiu-chang Towm Xintang Industrial Zone

# DECLARATION LETTER FROM INNOLUX



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About Us CSR Products Technology Investor Relations Careers Media Center Quality and Service

A Promise to Our Children's Children

HSM

Apr 25, 2012

CSR >> Green Vision >> Green Value Chain >> HSM

From the CEO's Desk
CMI's CSR commitment
Corporate Governance
- Board of Directors
- Internal Control System
- Code of Conduct
- Business Continuity Management

Green Vision
- Green Living
- Green Operations
  - GHG Management
  - Energy Management
  - Water Resources Management
  - Environment Impact Reduction
- Green Value Chain
  - Green Product
  - Resource Management
  - HSM
  - Energy Management
  - Materials Management
  - Green Supply Chain
- Green Environment

SER Management
Employee Care
- Health and Safety
- Recruitment and Employment
- Rewards and Benefits
- Training and Development
- Employee Relations
- Health and Safety

Contributions to Society
- Scholastic Contributions
- Arts and Culture
- Community Engagement
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Following the globalization of product markets and supply chains, CMI has established the CMI Restricted Substances Management Standard (II3QM-0044) upon the RoHS, REACH and worldwide regulatory requirements after integrating customer requirements and standards, and the opinions and recommendations of relevant stakeholders. At CMI, alternative material development and toxic substance minimization are the foci in toxic substance management.

Alternative Material Development: CMI is the first in the panel industry to develop and use eco-friendly paper-plastic as packaging materials. Particularly, these materials are made of waste newspapers and corrugated paper, which are non-toxic, lead-free, biodegradable and pollution-free. After thermal pressing at very high temperatures, waste newspaper and corrugated paper pulp turns into the required shaped packaging materials without using adhesives and available for disassembly for recycling and reuse. CMI further requested suppliers to use packaging materials meeting the EU directives and CMI standards. In 2010, CMI completely replaced all arsenic glass with arsenic-free glass.

Hazardous Substance Minimization: In 2010, CMI voluntarily expanded the scope of halogen-free products to new panel modules. In LCD displays, CMI launched cooperation with customers. Part of the products and components already met the halogen-free target. Also, in order to minimize the mercury content in products, CMI began turning to LED products in new product design in 2010. In the same year, CMI expanded the scope of VOC control in packaging materials. In 2011, CMI will include parts and components in the VOC control.

To pursue the continuous development of the IT electronics industry, promote the realization of RoHS, and enhance the standard of IT electronics in environmental protection, CMI participated in the China RoHS voluntary certification promoted by the Electronic Information Product Pollution Control Technology Center and CESI Certification Center of the Ministry of Industry and Information Technology.

As the first group of enterprises to participate in the RoHS voluntary certification in China, CMI launched aggressive cooperation with the Electronic Information Product Pollution Control Technology Center and CESI Certification Center to make early supply chain preparation by establishing a complete hazardous substance control system and quality assurance system. CMI passed two China RoHS certifications from CESI, including the China RoHS factory audit for 1.36"-10.2" LCM production and management; and the China RoHS product voluntary certification for the 1.36"-4.3" LCM.

Legal Info | Privacy Chimei Innolux Corporation Leading global producer of LCD panel solutions

# DECLARATION LETTER FROM TI

TEXAS INSTRUMENTS

## Material Declaration Certificate for Semiconductor Products

TI certifies to the best of its knowledge that TI's semiconductor products designated as "Pb-Free", "RoHS Exempt" or "Green" (defined below):

- Do not exceed Joint Industry Guide ("JIG") Ed 4.1 or IEC 62474 dB Regulated Substance thresholds.
- Are compliant with the threshold requirements of the European Union's Restriction on Use of Hazardous Substances Directive, 2002/95/EC ("RoHS1"), as well as the recast Directive 2011/65/EU ("RoHS 2").
- Meet the China Management Methods for controlling Pollution by Electronic Information Products ("China RoHS").
- Do not contain any of the Registration, Evaluation, Authorization and Restriction of Chemicals ("REACH") substances of very high concern (SVHC) above the regulatory threshold of 0.1%, including lists released through Dec 2012. (see http://focus.ti.com/en/download/qlty/TI_REACH_Statement.pdf for full REACH statement)

TI defines its "Pb-free", "RoHS Exempt" and "Green" products as follows:

**Pb-Free**: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS 1 and RoHS 2 requirements for all 6 RoHS substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes. Product is also fully compliant to GADSL requirements for electronics

**RoHS Exempt**: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with RoHS pursuant to an exemption.

**Green**: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Chlorine (Cl), Bromine (Br) and Antimony trioxide based flame retardants. Thresholds for brominated flame retardants (BFRs) and chlorinated flame retardants (CFRs) must meet the <=900ppm each and <=1500ppm sum of both. Antimony trioxide must meet the 1000ppm threshold requirement.

**Note**: Proprietary materials must be in full compliance to known regulatory requirements as well

TI semiconductor products NOT designated as "Pb-Free" or "Green" comply with RoHS 1 and RoHS 2 and China RoHS for all substances except Lead (Pb), which may be found in the leadframe plating or solder balls, or in one of the RoHS exempt applications, 5(a), 7(a), 7(c)-I or 15. For semiconductor products containing lead, the China RoHS EFUP is 50 years (www.ti.com/leadfree).

TI's position is that its semiconductor products are considered components under RoHS 1 & RoHS 2. Therefore, the CE marking, EU declaration of conformity, and internal product control provisions stipulated in Article 7 of RoHS 2 do not apply.

Evaluation modules (EVMs): TI's EVMs are "equipment specifically designed solely for the purposes of research and development only made available on a business-to-business basis" and, per Article 2(4)(j) of RoHS 2, are not subject to RoHS 2.

To the best of TI's knowledge, its packing materials (boxes, trays, etc) comply with EU Directive 2004/12/EC for Packaging and Packaging Waste Material.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at http://www.ti.com/sc/docs/stdterms.htm) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

Signature: Kyle Flessner

Name/Title: Kyle Flessner, Vice President, Worldwide Quality

Date: January 14, 2013

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# DECLARATION LETTER FROM NXP

2010-07-01
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## CERTIFICATE OF COMPLIANCE
## - RoHS Declaration -

NXP Semiconductors certifies that, to its best knowledge, semiconductor products designated to be:

- RoHS compliant (including all homogeneous sub-components – the pins, casing, internal parts) and meet the requirements of the EU-Directive 2002/95/EC (Restriction on Hazardous Substances, RoHS) and its amendments. This includes also the non use of DecaBromoDiphenylEther (Deca-BDE).

These semiconductor products can be recognized by the "RoHS compliant" logo on the box label. In addition, products that do not make use of a Lead exemption with the "Lead-free" logo. The intention is to make NXP products Lead-Free, when there is appropriate technology available and as long as there is no adverse effect on the NXP high quality standards.

Lead (Pb) is the last of the RoHS Substances to be removed since the other restricted substances were already not used in NXP semiconductor's products. NXP's term of "Lead-free" or "Pb-free" mean semiconductor products that are compatible with the current RoHS requirements for all six of the RoHS substances, including the requirement that Lead (Pb) does not exceed 1000ppm by weight, in all homogeneous subcomponent materials. Where designed to be soldered at high temperatures, NXP "Lead-free" products are suitable for use in specified "Lead-free" processes. This status is based on NXP's understanding of RoHS and NXP's knowledge of the materials that go into its products as of the date of disclosure of information.

To facilitate customer requirements to check compliance of the products of NXP Semiconductors, NXP has made the material content information available via the internet via: http://www.nxp.com/search/chemical_content/index.php

When reviewing the material content, a spreadsheet can be downloaded, for your convenience and further processing in chemical management systems like IMDS. Due to the availability of this service, it's NXP policy not to upload such material content data in customer systems.

The signature below verifies that statements above, including but not limited to any material composition data are, to the best of our knowledge, valid and accurate. However, NXP cannot warrant that products from NXP's customers, in which such NXP products are incorporated, will in turn comply with this RoHS Declaration.

NXP Semiconductors
Sustainability Office

Eric-Paul Schat
Senior Director & Sustainability Officer

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# APPENDIX II

# PHOTOGRAPHAS